

### SN74ALVC164245 16-BIT 2.5-V TO 3.3-V/3.3-V TO 5-V LEVEL-SHIFTING TRANSCEIVER

WITH 3-STATE OUTPUTS

SCAS416P-MARCH 1994-REVISED NOVEMBER 2005

FEATURES

- Member of the Texas Instruments Widebus™ Family
- Max t<sub>pd</sub> of 5.8 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Control Inputs VIH/VIL Levels Are Referenced to V<sub>CCA</sub> Voltage
- Latch-Up Performance Exceeds 250 mA Per JESD 17

NOTE: New and improved versions of the SN74ALVC164245 are available. The new part numbers are SN74LVC16T245 and SN74LVCH16T245 and should be considered for new designs.

# DESCRIPTION/ORDERING INFORMATION

This 16-bit (dual-octal) noninverting bus transceiver contains two separate supply rails. B port has V<sub>CCB</sub>, which is set to operate at 3.3 V and 5 V. A port has V<sub>CCA</sub>, which is set to operate at 2.5 V and 3.3 V. This allows for translation from a 2.5-V to a 3.3-V environment, and vice versa, or from a 3.3-V to a 5-V environment, and vice versa.

The SN74ALVC164245 is designed for asynchronous communication between data buses. The control circuitry (1DIR, 2DIR, 1OE, and 2OE) is powered by V<sub>CCA</sub>.

To ensure the high-impedance state during power up or power down, the output-enable (OE) input should be tied to  $V_{\text{CC}}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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	. U		
1DIR	1	48	] 1 <u>0E</u>
1B1 [	2		1A1
1B2	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		1A2
GND [		_	GND
1B3 [		44	1A3
1B4 [	6	43	] 1A4
(3.3 V, 5 V) V <sub>CCB</sub> [	7	42	] V <sub>CCA</sub> (2.5 V, 3.3 V)
1B5 [	8	41	] 1A5
1B6	9	40	] 1A6
GND [	10	39	] GND
1B7 [	11	38	] 1A7
1B8 [	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND [	15	34	GND
2B3	16	33	2A3
2B4	17	32	2A4
(3.3 V, 5 V) V <sub>CCB</sub>	18	31	V <sub>CCA</sub> (2.5 V, 3.3 V)
2B5			2A5
2B6	20	29	2A6
GND			GND
2B7			2A7
2B8			2A8
2DIR		25	20E
ON			COMP.

T <sub>A</sub>	PACKA	GE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	FBGA – GRD	Tene and see (	74ALVC164245GRDR	VOADAE
	FBGA – ZRD (Pb-free)	Tape and reel	74ALVC164245ZRDR	- VC4245
	1007.001	Tube of 25	SN74ALVC164245DL	100 . 100
	SSOP – DL	Deel of 1000	SN74ALVC164245DLR	ALVC164245
	WW.100 CO	Reel of 1000	74ALVC164245DLRG4	WWW.LOOY.C
–40°C to 85°C	N.1001.	Dec. 4 ( 0000	SN74ALVC164245DGGR	WW.IO
	TOOD DOO	Reel of 2000	74ALVC164245DGGRG4	1001
	TSSOP – DGG	Dest 4050	SN74ALVC164245DGGT	- ALVC164245
	WW.100	Reel of 250	74ALVC164245DGGTE4	WWW.Loo
	VFBGA – GQL	Deal of 4000	SN74ALVC164245KR	VGADAE
	VFBGA – ZQL (Pb-free)	Reel of 1000	74ALVC164245ZQLR	- VC4245

#### **ORDERING INFORMATION**

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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# **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

The logic levels of the direction-control (DIR) input and the output-enable (OE) input activate either the B-port outputs or the A-port outputs or place both output ports into the high-impedance mode. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports always is active and must have a logic HIGH or LOW level applied to prevent excess I<sub>CC</sub> and I<sub>CCZ</sub>.

**GQL OR ZQL PACKAGE** OY.COM.TW (TOP VIEW) . . . . .

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К	000000	
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TERMINAL ASSIGNMENTS <sup>(1)</sup>	
(56-Ball GQL/ZQL Package)	

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V <sub>CCB</sub>	V <sub>CCA</sub>	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7		M.L	1A7	1A8
F	2B1	2B2	001.0		2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
H	2B5	2B6	V <sub>CCB</sub>	V <sub>CCA</sub>	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 <mark>OE</mark>

(1) NC – No internal connection

o internal connection	
TERMINAL ASSIGNME (54-Ball GRD/ZRD Pag	

ON.	1	2	3	4	5	
Α	1B1	NC	1DIR	1OE	NC	1
В	1B3	1B2	NC	NC	1A2	1
C	1B5	1B4	V <sub>CCB</sub>	V <sub>CCA</sub>	1A4	1/
D	1B7	1B6	GND	GND	1A6	1/
E	2B1	1B8	GND	GND	1A8	2/
FC	2B3	2B2	GND	GND	2A2	2/
G	2B5	2B4	V <sub>CCB</sub>	V <sub>CCA</sub>	2A4	24
0н.	2B7	2B6	NC	NC	2A6	2 <i>F</i>
J	2B8	NC	2DIR	2OE	NC	2A

# FUNCTION TABLE<sup>(1)</sup> (EACH 8-BIT SECTION)

CONTRO	L INPUTS	OUTPUT O	CIRCUITS	OPERATION	
OE	DIR	A PORT	B PORT	OPERATION	
L	N.C	Enabled	Hi-Z	B data to A bus	
NVL-IV	J.H.O.	Hi-Z	Enabled	A data to B bus	
. н. 10	X	Hi-Z	Hi-Z	Isolation	

(1) Input circuits of the data I/Os always are active.

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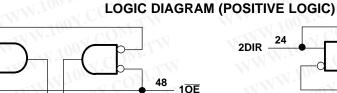
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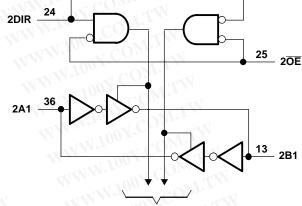
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1DIR

1





**To Seven Other Channels** 

# Absolute Maximum Ratings<sup>(1)</sup>

**To Seven Other Channels** 

over operating free-air temperature range for V<sub>CCB</sub> at 5 V and V<sub>CCA</sub> at 3.3 V (unless otherwise noted)

2

1**B**1

MIL	WT WT.	TIOOY.CONLTN NI	MIN MAX	UNIT
V		V <sub>CCA</sub>	-0.5 4.6	V
V <sub>CC</sub>	Supply voltage range	V <sub>CCB</sub>	-0.5 6	
W.	N 1002. M.TV	Except I/O ports <sup>(2)</sup>	-0.5 6	]- - • 1
V	Input voltage range	I/O port A <sup>(3)</sup>	-0.5 V <sub>CCA</sub> + 0.5	V
	WW.LOCONI. TW	I/O port B <sup>(2)</sup>	-0.5 V <sub>CCB</sub> + 0.5	WT
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0	-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>0</sub> < 0	-50	mA
I <sub>O</sub>	Continuous output current	WWW 100X.CONTR	±50	mA
	Continuous current through each $V_{CC}$ or G	ND	±100	mA
W.100		DGG package	70	COMP
A 100X	Declares the secol increasing (4)	DL package	63	0000
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	GQL/ZQL package	42	°C/W
		GRD/ZRD package	36	A.COM
T <sub>stg</sub>	Storage temperature range	COM-	-65 150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) This value is limited to 6 V maximum.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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#### Recommended Operating Conditions<sup>(1)</sup>

Mr.	No. 1. WWW.	COMPANY WWW.	VT	MIN	MAX	UNIT
V <sub>CCB</sub>	Supply voltage		OM.	3	5.5	V
VIH	High-level input voltage	I. M.TW W. M. 1001.	COM.I	2		V
	Low lovel input voltage	V <sub>CCB</sub> = 3 V to 3.6 V	NIT?		0.7	V
VIL	Low-level input voltage	V <sub>CCB</sub> = 4.5 V to 5.5 V	COMP.	N	0.8	v
VIB	Input voltage	10 1. COM. 1	COM-	0	$V_{CCB}$	V
V <sub>OB</sub>	Output voltage		N.C.	0	$V_{CCB}$	V
I <sub>OH</sub>	High-level output current	WWWW	01.00	WT	-24	mA
l <sub>OL</sub>	Low-level output current	The CONT.	N.COM	Wm	24	mA
Δt/Δv	Input transition rise or fall rate	N.100 . COM. I	1001	1.1	10	ns/V
T <sub>A</sub>	Operating free-air temperature	100X.CONTW WW	1001.	-40	85	°C

All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004. (1)WW.100Y.COM

### Recommended Operating Conditions<sup>(1)</sup>

	100 1. COM. I.	COM. I COM. I NWW. 100	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage		2.3	3.6	V
V High lovel input veltage		V <sub>CCA</sub> = 2.3 V to 2.7 V	1.7	TIM	V
VIH	IH High-level input voltage	V <sub>CCA</sub> = 3 V to 3.6 V	2	Jur	V
V <sub>II</sub> Low-level input voltage		V <sub>CCA</sub> = 2.3 V to 2.7 V		0.7	V
VIL VIL	Low-level input voltage	V <sub>CCA</sub> = 3 V to 3.6 V	100 1	0.8	V
V <sub>IA</sub>	Input voltage	WWWWWWWWWWWWWWWWWWWWWWW	0	V <sub>CCA</sub>	V
√ <sub>OA</sub>	Output voltage	WWW.LOW CONTENN WW	0	V <sub>CCA</sub>	V
	100° M.I.	$V_{CCA} = 2.3 V$	14.100	-18	mA
ОН	High-level output current	V <sub>CCA</sub> = 3 V	100	-24	
		V <sub>CCA</sub> = 2.3 V	11	18	mA
OL	Low-level output current	$V_{CCA} = 3 V$	WW.L	24	mA
∆t/∆v	Input transition rise or fall rate	W.100 L. COM.	.WW.	10	ns/V
Γ <sub>A</sub>	Operating free-air temperature	W WW JOY CTW	-40	85	°C

All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, (1) WW.100Y.COM.TV Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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#### **Electrical Characteristics**

over recommended operating free-air temperature range for V<sub>CCA</sub> = 2.7 V to 3.6 V and V<sub>CCB</sub> = 4.5 V to 5.5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP <sup>(1)</sup> M	AX UNI
05	WT	I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V	1001.	$V_{CC} - 0.2$		
	B to A	1 12 m4	2.7 V	V.C.	2.2		
	D IO A	$I_{OH} = -12 \text{ mA}$	3 V	NW.IO	2.4		
N S	WT.M	$I_{OH} = -24 \text{ mA}$	3 V	W.1001	2	v	
V <sub>OH</sub>	WT	100.04	LU VI	4.5 V	4.3	1	v
	A to D	I <sub>OH</sub> = -100 μA	W	5.5 V	5.3	WT	
	A to B	1 34 m 4 5 1 2 0 1		4.5 V	3.7	- N	
	WT.M	I <sub>OH</sub> = -24 mA	M.T.Y	5.5 V	4.7	U.L.	
	B to A	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V	WW	001.00	N.T.W	).2
		I <sub>OL</sub> = 12 mA	2.7 V	WWW.	.V.CU	WT	).4
VOL		I <sub>OL</sub> = 24 mA	3 V	WW	. C	0.	55 V
	A to D	I <sub>OL</sub> = 100 μA	T.INO	4.5 V to 5.5 V	v.100 r.	M.L.	).2
	A to B	I <sub>OL</sub> = 24 mA	WT	4.5 V to 5.5 V	-100Y.	0.	55
h.	Control inputs	$V_{I} = V_{CCA}/V_{CCB}$ or GND	3.6 V	5.5 V	Voo.	.Com	±5 μΑ
I <sub>OZ</sub> <sup>(2)</sup>	A or B port	$V_{O} = V_{CCA}/V_{CCB}$ or GND	3.6 V	5.5 V	W.IV	1 CON- +	10 μA
Icc	1001.00	$V_{I} = V_{CCA}/V_{CCB}$ or GND, $I_{O} = 0$	3.6 V	5.5 V	100 NN 100	MON	40 μA
ΔI <sub>CC</sub> <sup>(3</sup>	3)	One input at $V_{CCA}/V_{CCB} - 0.6 V$ , Other inputs at $V_{CCA}/V_{CCB}$ or GND	3 V to 3.6 V	4.5 V to 5.5 V	WW.10	N.CONT	50 μΑ
Ci	Control inputs	$V_{I} = V_{CCA}/V_{CCB}$ or GND	3.3 V	5 V	1.1	6.5	pF
Cio	A or B port	$V_{O} = V_{CCA}/V_{CCB}$ or GND	3.3 V	3.3 V	MW	8.5	pF

(1)

(2)

Typical values are measured at  $V_{CCA} = 3.3$  V and  $V_{CCB} = 5$  V,  $T_A = 25^{\circ}$ C. For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current. This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than at 0 or the associated (3)V<sub>CC</sub>.

#### **Electrical Characteristics**

over recommended operating free-air temperature range for  $V_{CCA}$  = 2.3 V to 2.7 V and  $V_{CCB}$  = 3 V to 3.6 V (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	MAX	UNIT
		I <sub>OH</sub> = -100 μA	2.3 V to 2.7 V	3 V to 3.6 V	V <sub>CCA</sub> - 0.2		CO.
	он A to B	$I_{OH} = -8 \text{ mA}$	2.3 V	3 V to 3.6 V	1.7	1.100	
V <sub>он</sub>		$I_{OH} = -12 \text{ mA}$	2.7 V	3 V to 3.6 V	1.8	¥.100	V
		I <sub>OH</sub> = -100 μA	2.3 V to 2.7 V	3 V to 3.6 V	V <sub>CCB</sub> – 0.2		
		I <sub>OH</sub> = -18 mA	2.3 V to 2.7 V	3 V	2.2	NN.Y	
	B to A	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V		0.2	00 -
,		I <sub>OL</sub> = 12 mA	2.3 V	3 V to 3.6 V		0.6	100
V <sub>OL</sub>	A to D	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V		0.2	V
	A to B	I <sub>OL</sub> = 18 mA	2.3 V	3 V	N	0.55	
1	Control inputs	$V_{I} = V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V		±5	μA
oz <sup>(1)</sup>	A or B port	$V_{O} = V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V	IN I	±10	μA
cc		$V_{I} = V_{CCA}/V_{CCB}$ or GND, $I_{O} = 0$	2.3 V to 2.7 V	3 V to 3.6 V	WT.	20	μA
ΔI <sub>CC</sub> <sup>(2)</sup>		One input at $V_{CCA}/V_{CCB} - 0.6 V$ , Other inputs at $V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V	WILL	750	μΑ

For I/O ports, the parameter  $\mathrm{I}_{\mathrm{OZ}}$  includes the input leakage current. (1)

This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than at 0 or the associated (2) V<sub>CC</sub>.

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#### Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 4)

	EDOM.	M.TN TO V	V <sub>CCB</sub> = 3.3 V ± 0.3 V	Mon	$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CCA</sub> = 2.5 V ± 0.2 V	V <sub>CCA</sub>	V <sub>CCA</sub> = 2.7 V		: 3.3 V 3 V	UNIT
	WW 100Y.	M.TW	MIN MA	X MIN	MAX	MIN	MAX	
COM. TW	A	В	7	.6	5.9	1	5.8	ns
t <sub>pd</sub>	В	COM A	7	.6	6.7	1.2	5.8	
t <sub>en</sub>	OE	В	11	.5	9.3	1	8.9	ns
t <sub>dis</sub>	OE	В	10	.5	9.2	2.1	9.5	ns
t <sub>en</sub>	OE	A N	12	.3	10.2	2	9.1	ns
t <sub>dis</sub>	OE	A O A	9	.3	9	2.9	8.6	ns

# **Operating Characteristics**

	PARAMETER		TEST CONDITIONS	V <sub>CCB</sub> = 3.3 V V <sub>CCA</sub> = 2.5 V	V <sub>CCB</sub> = 5 V V <sub>CCA</sub> = 3.3 V	UNIT
			COM	TYP	ТҮР	_
A.	100Y. M.TW	Outputs enabled (B)		55	56	
	Development	Outputs disabled (B)	$-C_{L} = 50 \text{ pF}, \text{ f} = 10 \text{ MHz}$	27	6	pF
C <sub>pd</sub>	Power dissipation capacitance	Outputs enabled (A)		118	56	
		Outputs disabled (A)	$-C_{L} = 50 \text{ pF}, \text{ f} = 10 \text{ MHz}$	58	6	-

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#### **POWER-UP CONSIDERATIONS**(1)

TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. Take these precautions to guard against such power-up problems:

1. Connect ground before any supply voltage is applied.

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2. Power up the control side of the device (V<sub>CCA</sub> for all four of these devices).

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- 3. Tie  $\overline{OE}$  to V<sub>CCA</sub> with a pullup resistor so that it ramps with V<sub>CCA</sub>.
- 4. Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with V<sub>CCA</sub>. Otherwise, keep DIR low.
- (1) Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.

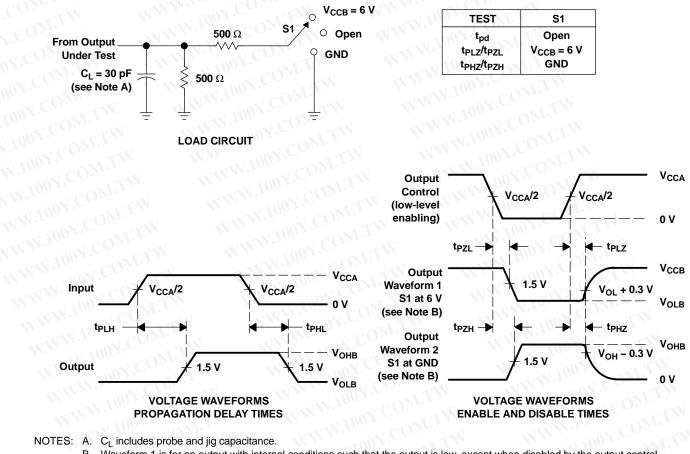
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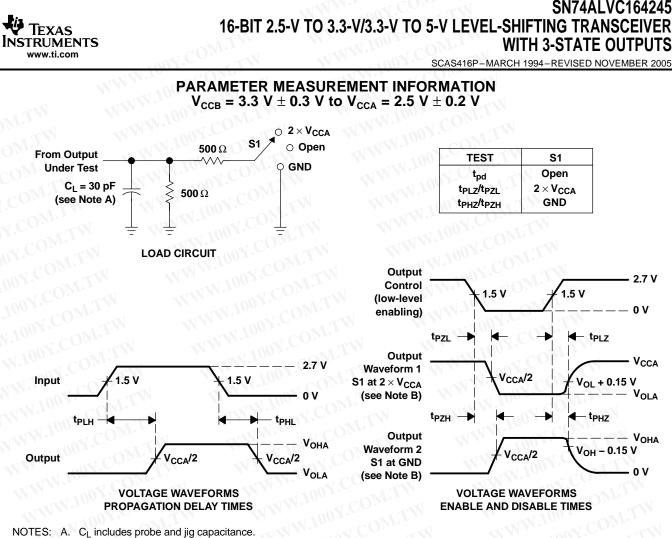


# PARAMETER MEASUREMENT INFORMATION $V_{CCA}$ = 2.5 V $\pm$ 0.2 V to $V_{CCB}$ = 3.3 V $\pm$ 0.3 V



- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz, Z<sub>0</sub> = 50  $\Omega$ , t<sub>f</sub> $\leq$ 2 ns, t<sub>f</sub> $\leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 1. Load Circuit and Voltage Waveforms



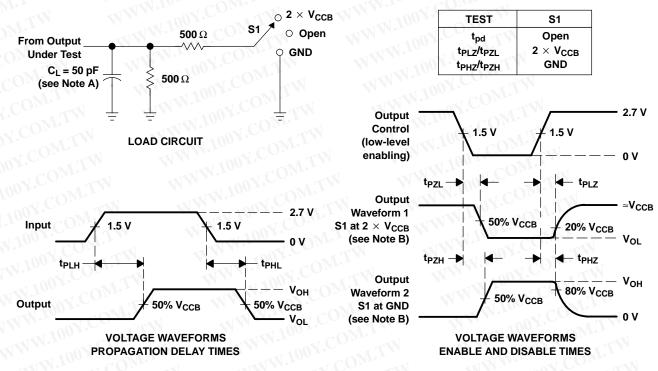
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>0</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2 ns, t<sub>r</sub>  $\leq$  2 ns. Ċ.
- The outputs are measured one at a time, with one transition per measurement. D.
- Ε. tPLZ and tPHZ are the same as tdis.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 2. Load Circuit and Voltage Waveforms

SCAS416P-MARCH 1994-REVISED NOVEMBER 2005



# PARAMETER MEASUREMENT INFORMATION $V_{CCA}$ = 3.3 V $\pm$ 0.3 V to $V_{CCB}$ = 5 V $\pm$ 0.5 V



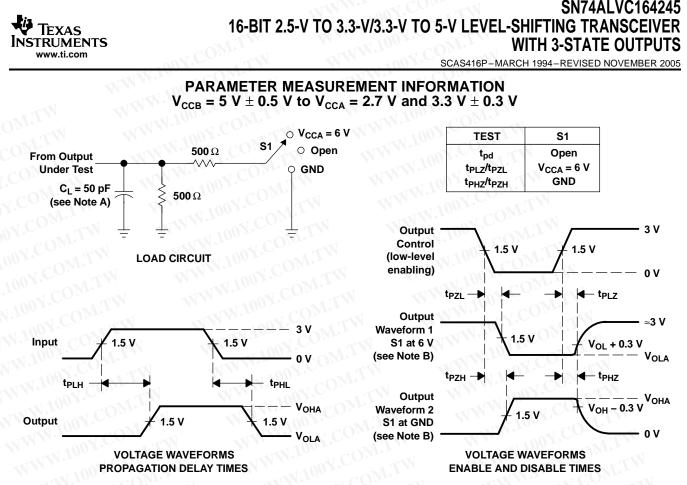
NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>f</sub> ≤ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

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- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 3. Load Circuit and Voltage Waveforms



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns. D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 4. Load Circuit and Voltage Waveforms

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27-Sep-2007

# **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVC164245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC164245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC164245DGGTE4	ACTIVE	TSSOP	DGG	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC164245DGGTG4	ACTIVE	TSSOP	DGG	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC164245DLG4	ACTIVE	SSOP		48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC164245DLRG4	ACTIVE	SSOP	C DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC164245GRDR	ACTIVE	BGA MI CROSTA R JUNI OR	GRD	54	1000	TBD	SNPB	Level-1-240C-UNLIM
74ALVC164245ZQLR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
74ALVC164245ZRDR	ACTIVE	BGA MI CROSTA R JUNI OR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SN74ALVC164245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC164245DGGT	ACTIVE	TSSOP	DGG	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC164245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC164245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC164245KR	ACTIVE	BGA MI CROSTA R JUNI OR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

# PACKAGE OPTION ADDENDUM



27-Sep-2007

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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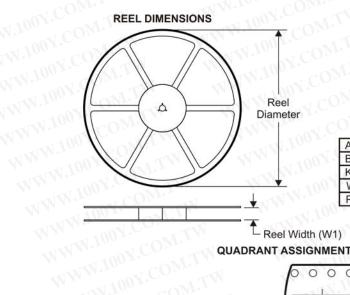
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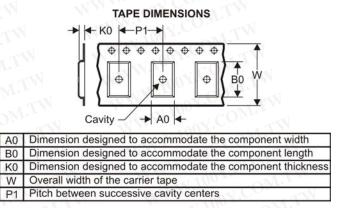
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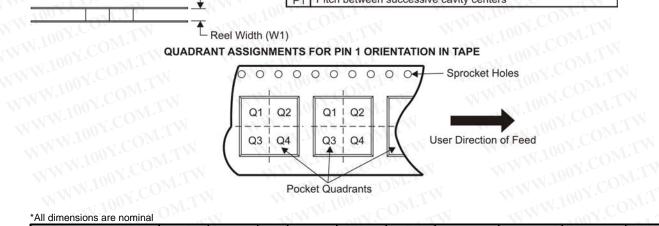
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#### TAPE AND REEL INFORMATION



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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVC164245GRDR	BGA MI CROSTA R JUNI OR	GRD	54	1000	330.0	16.4	5.8	8.3	1.55	8.0	16.0	Q1
74ALVC164245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
74ALVC164245ZRDR	BGA MI CROSTA R JUNI OR	ZRD	54	1000	330.0	16.4	5.8	8.3	1.55	8.0	16.0	Q1
SN74ALVC164245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ALVC164245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVC164245KR	BGA MI CROSTA R JUNI OR	GQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1

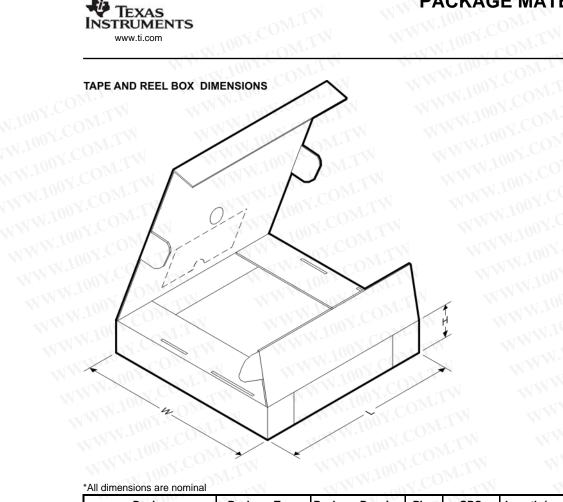
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# WWW.100Y.C **PACKAGE MATERIALS INFORMATION**

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVC164245GRDR	BGA MICROSTAR JUNIOR	GRD	54	1000	346.0	346.0	33.0
74ALVC164245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	346.0	346.0	33.0
74ALVC164245ZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	346.0	346.0	33.0
SN74ALVC164245DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ALVC164245DLR	SSOP	DL	48	1000	346.0	346.0	49.0
SN74ALVC164245KR	BGA MICROSTAR JUNIOR	GQL A	56	1000	346.0	346.0	33.0

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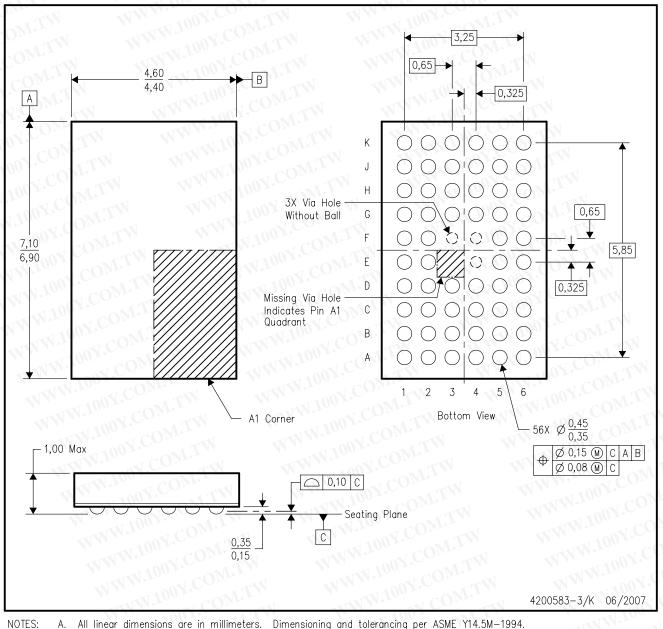
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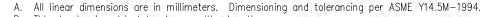
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GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY





- Β. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

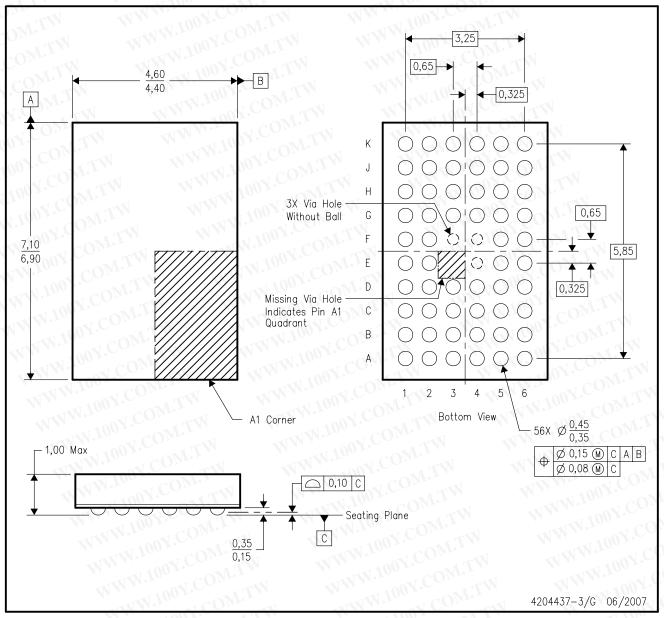
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ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

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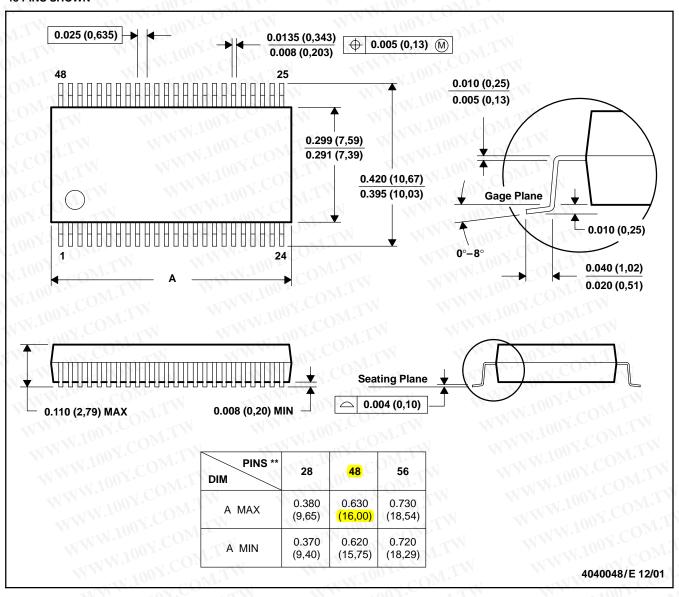
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# **MECHANICAL DATA**

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

#### DL (R-PDSO-G\*\*) 48 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118



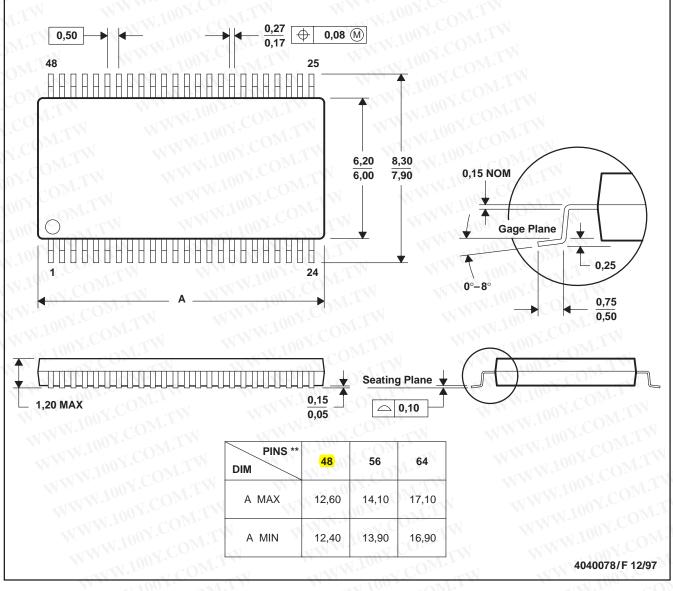
# **MECHANICAL DATA**

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

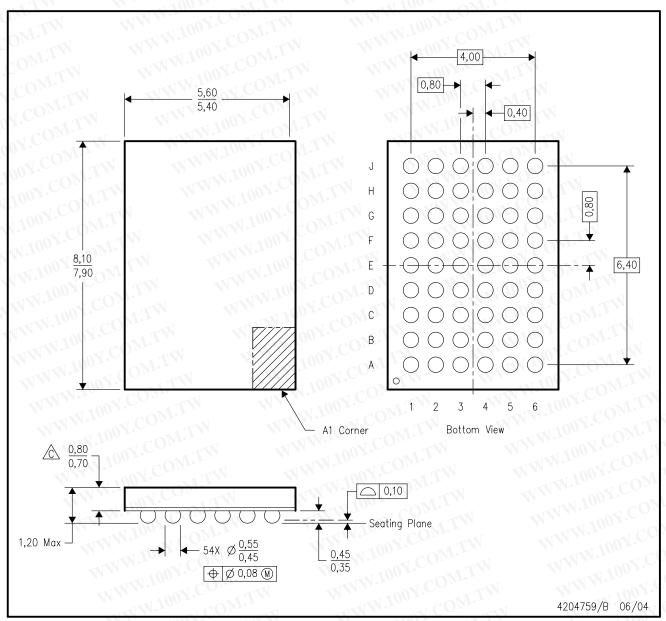
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.

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D. Falls within JEDEC MO-153



PLASTIC BALL GRID ARRAY



NOTES:

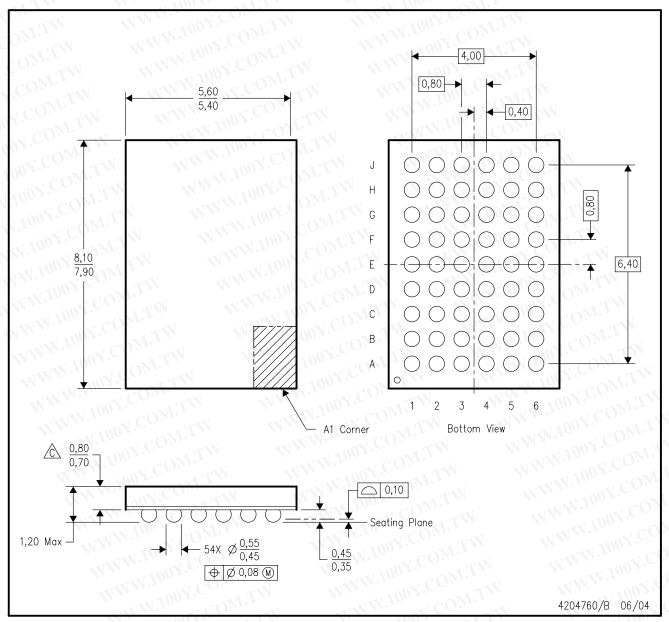
GRD (R-PBGA-N54)

- A. All linear dimensions are in millimeters. B. This drawing is subject to change without notice.
- Falls within JEDEC MO-205 variation DD.
- D. This package is tin-lead (SnPb). Refer to the 54 ZRD package (drawing 4204760) for lead-free.

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PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

ZRD (R-PBGA-N54)

- B. This drawing is subject to change without notice.
- $\land$  Falls within JEDEC MO-205 variation DD.
- D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).



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